

Gap Pad[®] 1000SF

July 2011

PRODUCT DESCRIPTION

Thermally Conductive, Silicone-Free Gap Filling Material

FEATURES AND BENEFITS

- Thermal conductivity: 0.9 W/m-K
- No silicone outgassing
- No silicone extraction
- Reduced tack on one side to aid in application assembly
- Electrically isolating



The new Gap Pad[®] 1000SF is a thermally conductive, electrically insulating, siliconefree polymer specially designed for silicone-sensitive applications. The material is ideal for applications with high standoff and flatness tolerances. Gap Pad[®] 1000SF is reinforced for easy material handling and added durability during assembly. The material is available with a protective liner on both sides of the material. The topside has reduced tack for ease of handling.

Note: To build a part number, visit our website at www.bergquistcompany.com.

TYPICAL PROPERTIES OF GAP PAD 1000SF PROPERTY IMPERIAL VALUE METRIC VALUE TEST METHOD Color Green Green Visual Reinforcement Carrier Fiberglass Fiberglass — Thickness (inch) / (mm) 0.010 to 0.125 0.254 to 3.175 ASTM D374

Thickness (inch) / (mm)	0.010 to 0.125	0.254 to 3.175	ASTM D374
Inherent Surface Tack (I- or 2-sided)	2	2	
Density (g/cc)	2.0	2.0	ASTM D792
Heat Capacity (J/g-K)	1.1	1.1	ASTM EI269
Hardness, Bulk Rubber (Shore 00) (1)	40	40	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	34	234	ASTM D575
Continuous Use Temp (°F) / (°C)	-76 to 257	-60 to 125	_
ELECTRICAL			
Dielectric Breakdown Voltage (Vac)	>6000	>6000	ASTM D149
Dielectric Constant (1000 Hz)	5.0	5.0	ASTM D150
Volume Resistivity (Ohm-meter)	I 0 ¹⁰	1 O ¹⁰	ASTM D257
Flame Rating	V- I	V- I	U.L. 94
THERMAL			
Thermal Conductivity (W/m-K)	0.9	0.9	ASTM D5470

1) Thirty second delay value Shore 00 hardness scale.

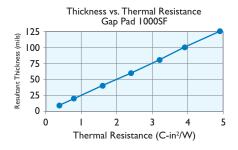
 Timin y second usery value output of the interse scale.
 Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². For more information on Gap Pad modulus, refer to Bergquist Application Note #116.

TYPICAL APPLICATIONS INCLUDE

- Digital disk drives / CD-ROM
- Automotive modules
- · Fiber optics modules

CONFIGURATIONS AVAILABLE

Sheet form and die-cut parts





Disclaimer

Note:

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Reference 0.1